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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/825,664  
Filing Date ..... April 3, 2001  
Inventor ..... David R. Hembree  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 2858  
Examiner ..... V. Nguyen  
Attorney's Docket No. .... MI22-1680  
Title: Electronic Device Wafer Processing Members and Wafer Processing Apparatuses

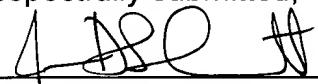
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -- See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. No admission is made regarding whether all the submitted references are prior art.

Dated: 5/10/02

Attorney:

Respectfully submitted,  
  
James D. Shaurette  
Reg. No. 39,833

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Form PTO-1449

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PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.  
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09/825,664LIST OF ART CITED BY APPLICANT  
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PATENT & TRADEMARK OFFICE  
U.S. PATENT DOCUMENTSAPPLICANT  
Micron Technology, Inc.FILING DATE  
April 3, 2001GROUP  
2858

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	5,886,863	3/23/1999	Nagasaki et al.			
	AB						
	AC						
	AD						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AE						
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	AG						
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	AJ						
	AK						
	AL						
EXAMINER				DATE CONSIDERED			

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Form PTO-1449				U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. MI22-1680	SERIAL NO. 09/825,664	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT David R. Hembree			
				FILING DATE April 3, 2001	GROUP 2858		
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	3,440,407	4/22/69	Golstos et al.			
	AB	3,614,345	10/19/71	Quinn			
	AC	3,683,306	8/8/72	Bulthuis et al.			
	AD	4,332,081	6/1/82	Francis			
	AE	4,518,944	5/21/83	Faris			
	AF	4,703,555	11/3/87	Hubner			
	AG	5,141,334	8/25/92	Castles			
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	AK	5,446,437	8/29/95	Bantien et al.			
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
	AL	2336778	7/1977	France			Yes
	AM	56-12521	2/1981	Kobayashi, Japan			No
	AN	2-268462	11/1990	Yamanishi, Japan			
	AO						
	AP						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AR	/	Application Guide Temperature Sensors. Welsch Electrical Manufacturing Company Catalog, pp. 773-778, 1992/1993.				
	AS	/	In-Situ Survey System of Resistive and Thermoelectric Properties of Either Pure or Mixed Materials in Thin Films Evaporated Under Ultra High Vacuum. Lebevallier, Lethuera, Richou, Serre, & Gouault, J. Phys. III France, Vol. 5, pp. 409-418, 04/95 (Abstract only).				
	AT	/	Temperature Metrology for CD Control in DUV Lithography. Jeffrey Parker and Wayne Renken, pp. 111-112, 114, 116, 09/17/97.				
EXAMINER				DATE CONSIDERED			
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	AP		"NTC and PTC Thermistors"; <a href="http://www.thermodisc.com/ntcptc.html">http://www.thermodisc.com/ntcptc.html</a> ; 1/7/98; 2 pages.																																																																								
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	AU		"Silicon Processing for the VLSI Era"; Volume 1 - Process Technology, Second Edition; S. Wolf et al.; 2000; pps 22-25 and pps. 841-845.																																																																								
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